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#### **QUADRUPLE 2-INPUT NAND GATES WITH SCHMITT TRIGGER INPUTS**

#### **Description**

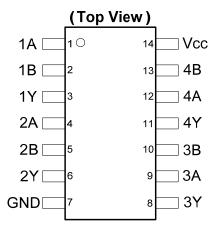
The 74LV132A provides provides four independent 2-input NAND gates with standard push-pull outputs. Each input is a Schmitt Trigger device with a significant amount of hysteresis suiting the device for noisy environments. The device is designed for operation with a power supply range of 2.0V to 5.5V.

The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output preventing damaging current backflow when the device is powered down.

The gates perform the Boolean function:

$$Y = \overline{A \bullet B} \ \text{or} \ Y = \overline{A} + \overline{B}$$

#### **Pin Assignments**



SO-14 / TSSOP-14

#### **Features**

- Wide Supply Voltage Range from 2.0V to 5.5V
- Sinks or sources 12mA at V<sub>CC</sub> = 4.5V
- CMOS low power consumption
- I<sub>OFF</sub> Supports Partial -Power Down Operation
- Inputs or Outputs accept up to 5.5V
- Inputs can be driven by 3.3V or 5V allowing for voltage translation applications.
- Schmitt Trigger Action at All Inputs
- ESD Protection Tested per JESD 22
  - Exceeds 200-V Machine Model (A115)
  - Exceeds 2000-V Human Body Model (A114)
  - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Applications**

- General Purpose Logic
- Power Down Signal Isolation
- · Wide array of products such as:
  - PCs, networking, notebooks, ultrabooks, netbooks
  - Computer peripherals, hard drives, CD/DVD ROM
  - TV, DVD, DVR, set top box

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

**Click for Ordering Information** 

October 2013

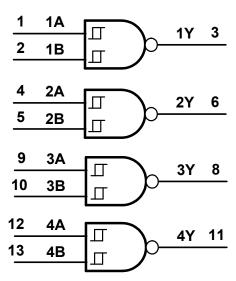
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#### **Pin Descriptions**

Pin Number	Pin Name	Description
1	1A	Data Input
2	1B	Data Input
3	1Y	Data Output
4	2A	Data Input
5	2B	Data Input
6	2Y	Data Output
7	GND	Ground
8	3Y	Data Output
9	3A	Data Input
10	3B	Data Input
11	4Y	Data Output
12	4A	Data Input
13	4B	Data Input
14	Vcc	Supply Voltage

## **Logic Diagram**



## **Function Table**

Inp	Output	
Α	В	Y
Н	Н	L
L	X	Н
X	L	Н

## **Absolute Maximum Ratings (Note 4)**

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to 7.0	٧
VI	Input Voltage Range note 4	-0.5 to 7.0	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < 0V	-20	mA
lok	Output Clamp Current V <sub>O</sub> < -0V	-50	mA
lo	Continuous Output Current - 0.5V < V <sub>O</sub> V <sub>CC</sub> + 0.5V	+/- 25	mA
Icc	Continuous Current Through Vcc	50	mA
I <sub>GND</sub>	Continuous Current Through GND	-50	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>TOT</sub>	Total Power Dissipation	500	mW

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



## **Recommended Operating Conditions (Note 5)**

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	-	2.0	5.5	V
VI	Input Voltage	1	0	5.5	V
Vo	Output Voltage	ı	0	V <sub>CC</sub>	V
	High-Level Output Current	2.0V	_	-50	mA
		2.3V to 2.7V	_	-2	μA
Іон		3.0V to 3.6V	-	-6	mA
		4.5V to 5.5V	_	-12	mA
		2.0V	_	50	μA
	Low-Level Output Current	2.3V to 2.7V	_	2	mA
l <sub>OL</sub>	Low-Level Output Current	3.0V to 3.6V	-	6	mA
		4.5V to 5.5V	_	12	mA
T <sub>A</sub>	Operating Free-Air Temperature	-	-40	+125	°C

Note: 5. Unused inputs should be held at Vcc or Ground.

## **Electrical Characteristics**

				T <sub>A</sub> = -40 to +85°C		T <sub>A</sub> = -40 f	to +125°C	1114
Symbol	Parameter	Parameter Test Conditions	Vcc	Min	Max	Min	Max	Unit
		_	2.5 V	1	1.75	1	1.75	
V <sub>T+</sub>	Positive Going Threshold	_	3.3 V	1.31	2.31	1.31	2.31	V
	σσσ.α	_	5.0 V	1.95	3.5	1.95	3.5	
		_	2.5 V	0.75	1.5	0.75	1.5	
$V_{T-}$	Negative Going Threshold	_	3.3 V	0.99	2.07	0.99	2.07	_
		_	5.0 V	1.5	3.05	1.5	3.05	
		_	2.5 V	0.25	1	0.25	1	
V <sub>H</sub>	Hysteresis (V <sub>T+-</sub> V <sub>T-)</sub>	_	3.3 V	0.33	1.32	0.33	1.32	V
	(*11.2.1.)	_	5.0 V	0.5	2	0.5	2	
		I <sub>OH</sub> = -50μA	2.0V to 5.5V	V <sub>CC</sub> -0.1	_	V <sub>CC</sub> -0.1	-	
	High-Level	I <sub>OH</sub> = -2mA	2.3V	2.0	-	2.0	-	
V <sub>OH</sub>	Output Voltage	I <sub>OH</sub> = -6mA	3.0V	2.48	-	2.48	-	V
		I <sub>OH</sub> = -12mA	4.5V	3.8	_	3.8	_	
		I <sub>OL</sub> = 50μA	2.0V to 5.5V	_	0.1	_	0.1	
V	Low-Level	I <sub>OL</sub> = 2mA	2.3V	-	0.4	-	0.4	V
$V_{OL}$	Output Voltage	I <sub>OL</sub> = 6mA	3.0V	-	0.44	-	0.44	]
		I <sub>OL</sub> = 12mA	4.5V	-	0.55	-	0.55	
I <sub>OFF</sub>	Power Down Leakage Current	$V_I$ or $V_O = 0$ to 5.5V	0V	_	5	_	5	μΑ
Iı	Input Current	V <sub>I</sub> =GND or 5.5V	0 to 5.5V	-	±1	-	±1	μΑ
Icc	Supply Current	V <sub>I</sub> = GND or V <sub>CC</sub> I <sub>O</sub> =0	5.5V	_	20	_	20	μΑ



## **Switching Characteristics**

Symbol	Symbol Parameter		V		T <sub>A</sub> = +25°(	;	-40 to	+85°C	-40 to	+125°C	Unit
Syllibol	Parameter	Conditions	V <sub>CC</sub>	Min	Тур.	Max	Min	Max	Min	Max	Onit
		Figure 1	2.5V ± 0.2V	-	7.9	16.5	1	18.5	1	18.5	
	t <sub>PD</sub> Propagation Delay A <sub>N</sub> to Y <sub>N</sub> Figure 1 C <sub>L</sub> =15pF Figure 1 C <sub>L</sub> =50 pF		3.3V ± 0.3V	-	5.6	11.9	1	14	1	14	ns
		5.0V ± 0.5V	-	3.9	7.7	1	9	1	9		
t <sub>PD</sub>		2.5V ± 0.2V	_	10.8	20.2	1	23	1	23		
			3.3V ± 0.3V	_	7.6	15.4	1	17.5	1	17.5	ns
			5.0V ± 0.5V	_	5.3	9.7	1	11	1	11	1

# Operating Characteristics T<sub>A</sub> = +25°C

Parameter		Test Conditions	V <sub>CC</sub>	TYP	Unit
0	Power Dissipation	F= 10 MHz	3.3V	7.5	pF
$C_{pd}$	Capacitance per Gate	C <sub>L</sub> =50pF	5.0V	11.2	ρг

#### **Noise Characteristics**

 $V_{CC} = 3V, C_L = 50pF, T_A = +25^{\circ}C$ 

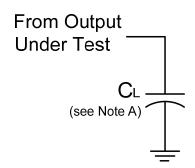
Symbol	Parameter	Min	Тур.	Max	Unit
$V_{OL(p)}$	Quiet output, maximum dynamic V <sub>OL</sub>	-	0.2	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V <sub>OL</sub>	_	-0.1	-0.8	V
V <sub>OH(V)</sub>	Quiet output, minimum dynamic V <sub>OH</sub>	-	3.1	-	V
V <sub>IH(D)</sub>	High Level dynamic input voltage	2.31	_	_	V
V <sub>IL(D)</sub>	Low Level dynamic input voltage	-	_	0.99	V

## **Package Characteristics**

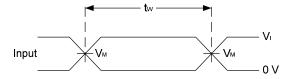
Symbol	Parameter	Test Conditions	Vcc	Min	Тур.	Max	Unit
Ci	Input Capacitance	$V_i = V_{CC} - \text{ or GND}$	2.0 to 5.5V	_	3.3	10	pF



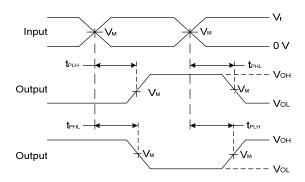
#### **Parameter Measurement Information**



V <sub>cc</sub>	Inp	outs	V <sub>M</sub>	CL
	VI	t <sub>r</sub> / t <sub>f</sub>		
2.0V to 5.5V	V <sub>CC</sub>	<3ns	V <sub>CC</sub> / 2	15pF or 50pF



Voltage Waveform Pulse Duration



Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

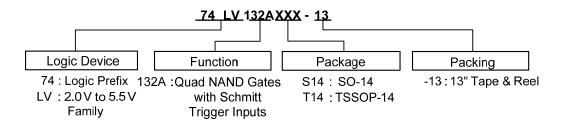
Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate  $\leq$  10MHz
- C. Inputs are measured separately one transition per measurement
- D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$

Figure 1. Load Circuit and Voltage Waveforms



#### **Ordering Information**



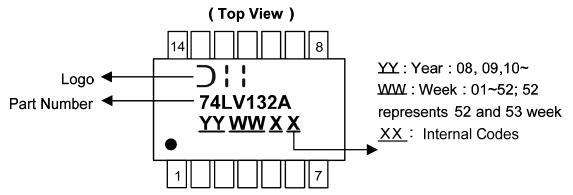
Device	Backago Codo	Packaging	13" Tape	and Reel
Device	Package Code	(Note 6)	Quantity	Part Number Suffix
74LV132AS14-13	S14	SO-14	2500/Tape & Reel	-13
74LV132AT14-13	T14	TSSOP-14	2500/Tape & Reel	-13

Note: 6. The tapir

6. The taping orientation and tape details can be found at http://www.diodes.com/datasheets/ap02007.pdf

#### **Marking Information**

#### (1) SO14, TSSOP14

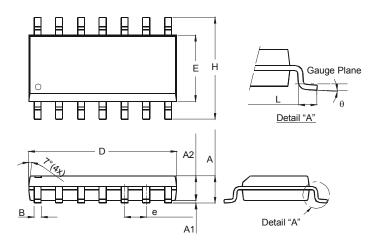


Part Number	Package
74LV132AS14	SO-14
74LV132AT14	TSSOP-14



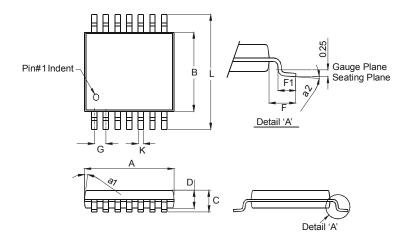
## Package Outline Dimensions (All Dimensions in mm)

#### Package Type: SO-14



SO-14			
Dim	Min	Max	
Α	1.47	1.73	
<b>A</b> 1	0.10	0.25	
A2	1.45 Typ		
В	0.33	0.51	
D	8.53	8.74	
Е	3.80	3.99	
е	1.27 Typ		
Н	5.80	6.20	
L	0.38	1.27	
θ	0°	8°	
All Dimensions in mm			

#### Package Type: TSSOP-14

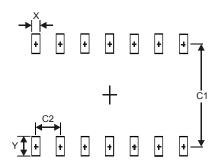


TSSOP-14		
Dim	Min	Max
a1	7° (4X)	
a2	0°	8°
Α	4.9	5.10
В	4.30	4.50
С		1.2
D	8.0	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
L	6.40 Typ	
All Dimensions in mm		



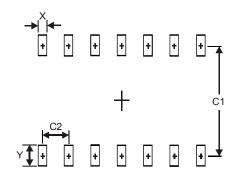
#### **Suggested Pad Layout**

Package Type: SO-14



Dimensions	Value (in mm)
Х	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65



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